Preferred Device

General Purpose Transistors

PNP Silicon

Features

• Pb-Free Packages are Available*

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector – Emitter Voltage	V _{CEO}	40	Vdc
Collector – Base Voltage	V _{CBO}	40	Vdc
Emitter – Base Voltage	V _{EBO}	5.0	Vdc
Collector Current – Continuous	۱ _C	600	mAdc
Total Device Dissipation @ T _A = 25°C Derate above 25°C	P _D	625 5.0	mW mW/°C
Total Device Dissipation @ T _C = 25°C Derate above 25°C	P _D	1.5 12	W mW/°C
Operating and Storage Junction Temperature Range	T _J , T _{stg}	–55 to +150	°C

THERMAL CHARACTERISTICS

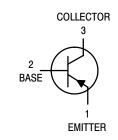
Characteristic	Symbol	Мах	Unit
Thermal Resistance, Junction-to-Ambient	R_{\thetaJA}	200	°C/W
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	83.3	°C/W

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.



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MARKING DIAGRAM



2N4403 = Device Code A = Assembly Location Y = Year WW = Work Week = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

© Semiconductor Components Industries, LLC, 2005 August, 2005 – Rev. 2 Preferred devices are recommended choices for future use and best overall value.

1

Publication Order Number: 2N4403/D

ELECTRICAL CHARACTERISTICS (T_A = 25° C unless otherwise noted)

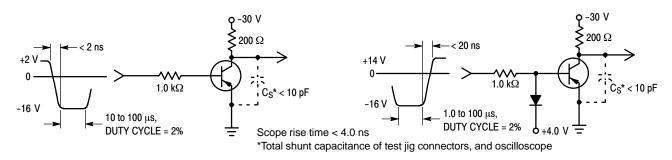
Characteristic		Symbol	Min	Max	Unit
OFF CHARACTERISTIC	CS	I			
Collector–Emitter Break ($I_C = 1.0 \text{ mAdc}, I_B = 0$	V _{(BR)CEO}	40	-	Vdc	
Collector-Base Breakd ($I_C = 0.1 \text{ mAdc}, I_E = 0.1 \text{ mAdc}$	V _{(BR)CBO}	40	-	Vdc	
Emitter–Base Breakdown Voltage ($I_E = 0.1 \text{ mAdc}, I_C = 0$)		V _{(BR)EBO}	5.0	-	Vdc
Base Cutoff Current ($V_{CE} = 35 \text{ Vdc}, V_{EB} = 0.4 \text{ Vdc}$)				0.1	μAdc
Collector Cutoff Current (V _{CE} = 35 Vdc, V _{EB} =	I _{CEX} –		0.1	μAdc	
ON CHARACTERISTIC	\$			ł	*
DC Current Gain $(I_{C} = 0.1 \text{ mAdc}, V_{CE} = 1.0 \text{ Vdc})$ $(I_{C} = 1.0 \text{ mAdc}, V_{CE} = 1.0 \text{ Vdc})$ $(I_{C} = 10 \text{ mAdc}, V_{CE} = 1.0 \text{ Vdc})$ $(I_{C} = 150 \text{ mAdc}, V_{CE} = 2.0 \text{ Vdc})$ (Note 1) $(I_{C} = 500 \text{ mAdc}, V_{CE} = 2.0 \text{ Vdc})$ (Note 1)		h _{FE}	30 60 100 100 20	- - 300 -	_
Collector-Emitter Saturation Voltage (Note 1) ($I_C = 150$ mAdc, $I_B = 15$ mAdc) ($I_C = 500$ mAdc, $I_B = 50$ mAdc)		V _{CE(sat)}	_	0.4 0.75	Vdc
Base – Emitter Saturation Voltage (Note 1) ($I_C = 150$ mAdc, $I_B = 15$ mAdc) ($I_C = 500$ mAdc, $I_B = 50$ mAdc)		V _{BE(sat)}	0.75	0.95 1.3	Vdc
SMALL-SIGNAL CHAR	ACTERISTICS				
Current–Gain – Bandwidth Product (I _C = 20 mAdc, V _{CE} = 10 Vdc, f = 100 MHz)		f _T	200	-	MHz
Collector–Base Capacitance (V_{CB} = 10 Vdc, I_E = 0, f = 1.0 MHz)		C _{cb}	_	8.5	pF
Emitter–Base Capacitance (V_{EB} = 0.5 Vdc, I_C = 0, f = 1.0 MHz)		C _{eb}	Ι	30	pF
Input Impedance ($I_C = 1.0 \text{ mAdc}$, $V_{CE} = 10 \text{ Vdc}$, $f = 1.0 \text{ kHz}$)		h _{ie}	1.5 k	15 k	Ω
Voltage Feedback Ratio (I_C = 1.0 mAdc, V_{CE} = 10 Vdc, f = 1.0 kHz)		h _{re}	0.1	8.0	X 10 ⁻⁴
Small–Signal Current Gain (I _C = 1.0 mAdc, V_{CE} = 10 Vdc, f = 1.0 kHz)		h _{fe}	h _{fe} 60 500		-
Output Admittance ($I_C = 1.0 \text{ mAdc}$, $V_{CE} = 10 \text{ Vdc}$, $f = 1.0 \text{ kHz}$)		h _{oe}	1.0	100	μmhos
SWITCHING CHARACT	ERISTICS				
Delay Time	$(V_{CC} = 30 \text{ Vdc}, V_{BE} = +2.0 \text{ Vdc},$	t _d	_	15	ns
Rise Time	$I_{\rm C} = 150 \text{ mAdc}, I_{\rm B1} = 15 \text{ mAdc})$	t _r	_	20	ns
Storage Time	$(V_{CC} = 30 \text{ Vdc}, I_C = 150 \text{ mAdc},$	t _s	-	225	ns
Fall Time	I _{B1} = 15 mA, I _{B2} = 15 mA)	t _f	-	30	ns

1. Pulse Test: Pulse Width \leq 300 µs, Duty Cycle \leq 2.0%.

ORDERING INFORMATION

Device	Package	Shipping [†]	
2N4403	TO-92	5,000 Units / Box	
2N4403G	TO–92 (Pb–Free)	5,000 Units / Box	
2N4403RL	TO-92	2,000 / Tape & Reel	
2N4403RLG	TO–92 (Pb–Free)	2,000 / Tape & Reel	
2N4403RLRA	TO-92	2,000 / Tape & Reel	
2N4403RLRAG	TO–92 (Pb–Free)	2,000 / Tape & Reel	
2N4403RLRM	TO-92	2,000 / Ammo Pack	
2N4403RLRMG	TO–92 (Pb–Free)	2,000 / Ammo Pack	
2N4403RLRP	TO-92	2,000 / Ammo Pack	
2N4403RLRPG	TO-92 (Pb-Free)	2,000 / Ammo Pack	

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.





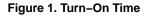
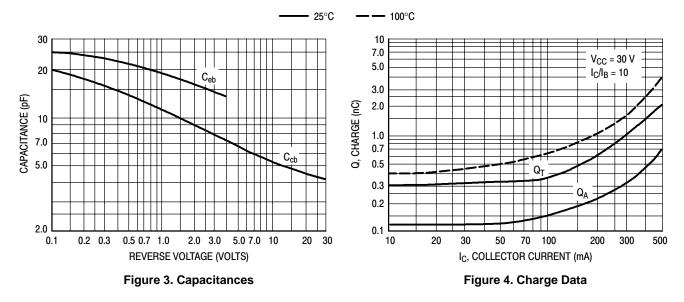
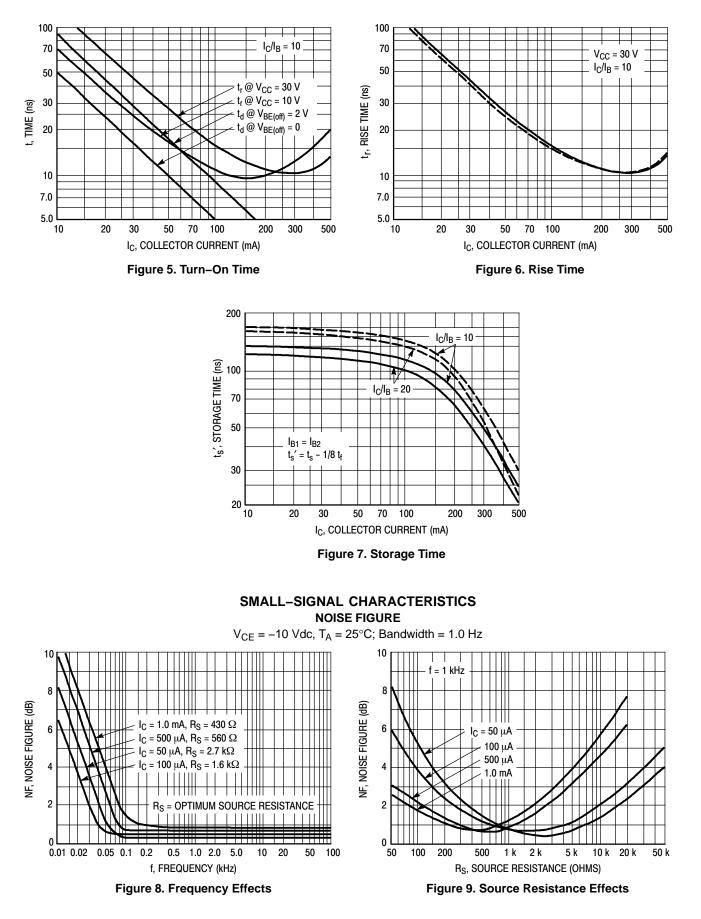


Figure 2. Turn–Off Time

TRANSIENT CHARACTERISTICS





h PARAMETERS

 $V_{CE} = -10 \text{ Vdc}, \text{ f} = 1.0 \text{ kHz}, \text{ T}_{A} = 25^{\circ}\text{C}$

This group of graphs illustrates the relationship between h_{fe} and other "h" parameters for this series of transistors. To obtain these curves, a high–gain and a low–gain unit were

selected from the 2N4403 lines, and the same units were used to develop the correspondingly–numbered curves on each graph.

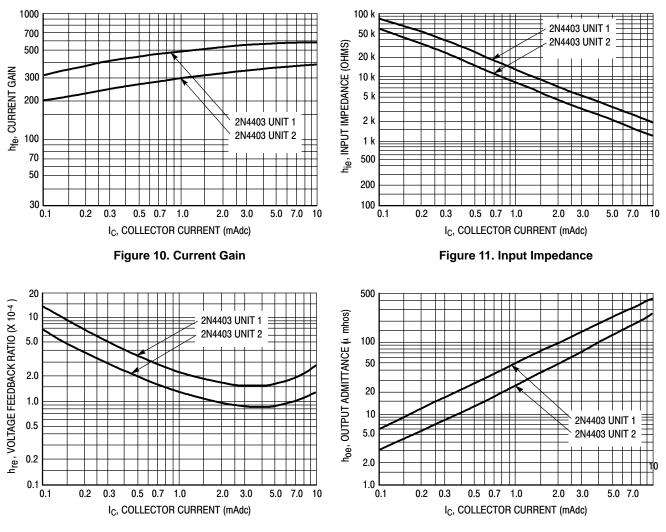
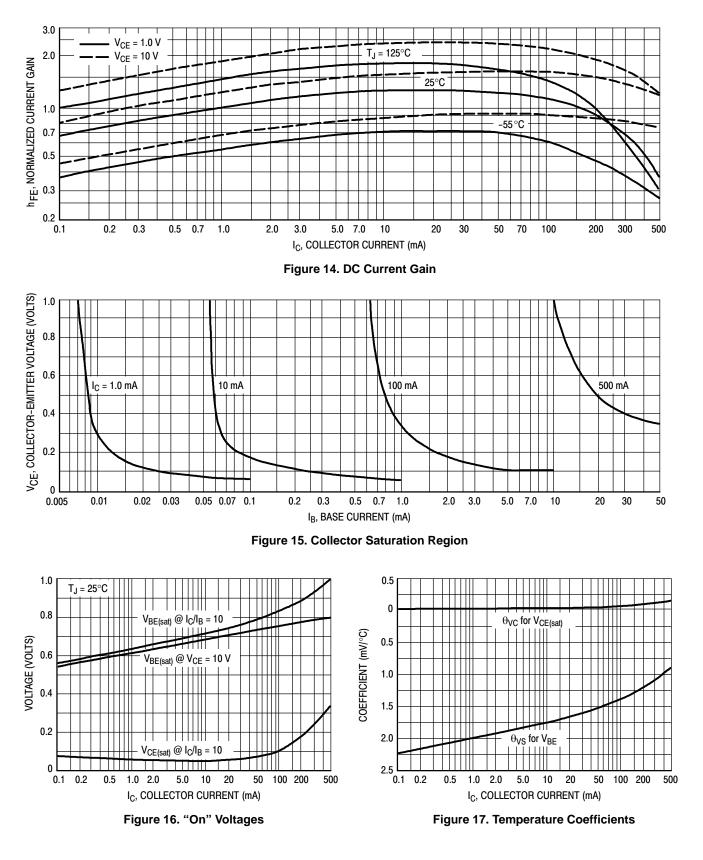


Figure 12. Voltage Feedback Ratio

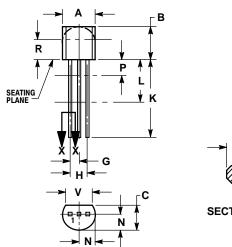
Figure 13. Output Admittance





PACKAGE DIMENSIONS

TO-92 **TO-226AA** CASE 29-11 **ISSUE AL**





NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- TIA-3M, 1962. CONTROLLING DIMENSION: INCH. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED. LEAD DIMENSION IS UNCONTROLLED IN P AND 2. 3.
- 4
- BEYOND DIMENSION K MINIMUM.

	INCHES		INCHES MILLIMETER	
DIM	MIN	MAX	MIN	MAX
Α	0.175	0.205	4.45	5.20
В	0.170	0.210	4.32	5.33
С	0.125	0.165	3.18	4.19
D	0.016	0.021	0.407	0.533
G	0.045	0.055	1.15	1.39
Н	0.095	0.105	2.42	2.66
ſ	0.015	0.020	0.39	0.50
K	0.500		12.70	
L	0.250		6.35	
Ν	0.080	0.105	2.04	2.66
Ρ		0.100		2.54
R	0.115		2.93	
۷	0.135		3.43	

STYLE 1: PIN 1. EMITTER

2. BASE

3. COLLECTOR

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